



HVC326C

Variable Capacitance Diode for UHF/VHF tuner

REJ03G0050-0100Z

Rev.1.00

Jul.07.2003

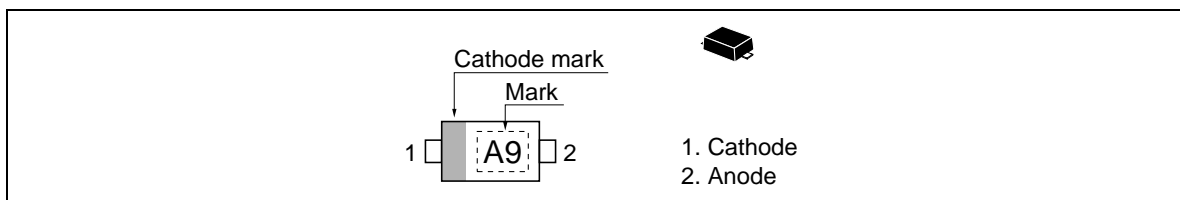
Features

- Low voltage type (tuning voltage 1 to 10 V), it is suitable for ET without DC/DC converter.
- Low series resistance. ($r_s = 0.6 \Omega$ max) and good C-V linearity.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVC326C	A9	UFP

Pin Arrangement



HVC326C**Absolute Maximum Ratings**

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	V _R	15	V
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Electrical Characteristics

(Ta = 25°C)

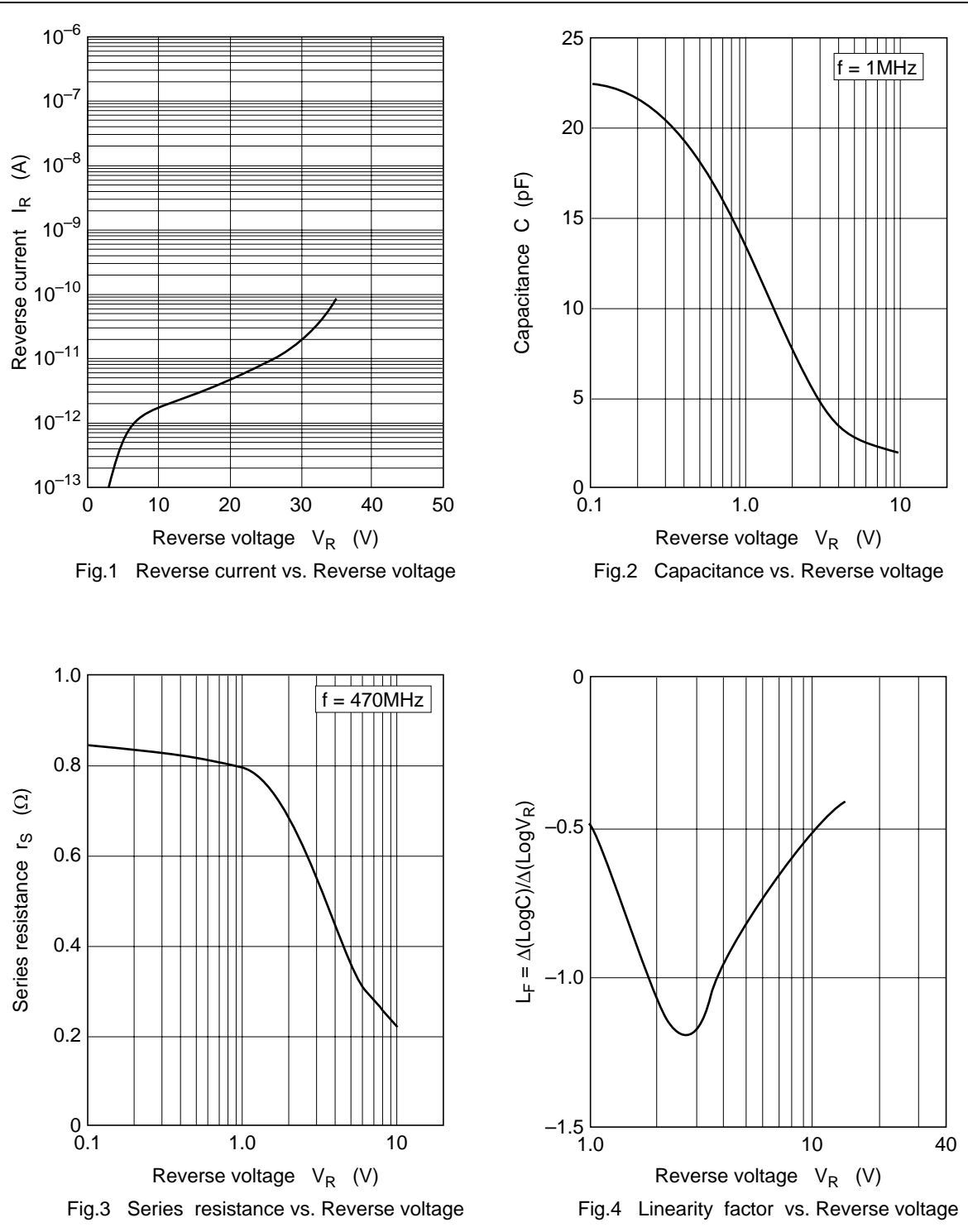
Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	I _{R1}	—	—	10	nA	V _R = 10 V
	I _{R2}	—	—	100		V _R = 10 V, Ta = 60°C
Capacitance	C ₁	13.0	—	16.0	pF	V _R = 1 V, f = 1 MHz
	C ₁₀	2.0	—	2.3		V _R = 10 V, f = 1 MHz
Capacitance ratio	n	6.0	—	—	—	C ₁ /C ₁₀
Series resistance	r _s	—	—	0.6	Ω	V _R = 5 V, f = 470 MHz
Matching error	ΔC/C *1	—	—	2.0	%	V _R = 1 to 10 V, f = 1 MHz

Note 1. C.C system (Continuous Connected taping system) enable to make any 10 pcs of ΔC/C continuous in a reel, expect extention to another group.
Calculate Matching Error,

$$\Delta C/C = \frac{(C_{\max} - C_{\min})}{C_{\min}} \times 100 (\%)$$

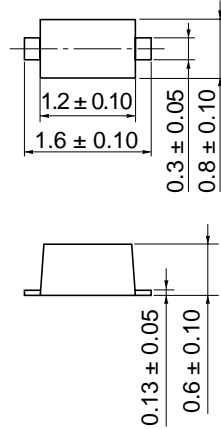
HVC326C

Main Characteristic



HVC326C**Package Dimensions**

As of January, 2003
Unit: mm



Package Code	UFP
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.0016 g

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